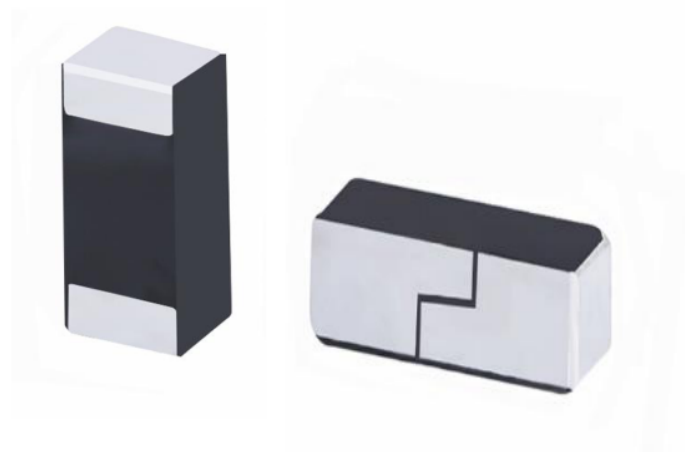


Series: Chip Antenna

TECHNICAL DATA SHEET

Description: **2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area**

PART NUMBER: W3008



Features:

- 2400-2483.5MHz
- Size: 3.2 x 1.6 x 1.1mm
- Efficiency: 66 %
- Gain: 1.1 dBi
- Polarization: Linear
- Power Handling: 5W
- RoHS Compliant
- Moisture Sensitivity Level MSL1

Applications:

- Bluetooth, BLE, Zigbee, WiFi
- 2.4GHz ISM band radios

All dimensions are in mm / inches

Issue: 1946

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

Series: Chip Antenna**Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area****PART NUMBER: W3008****ELECTRICAL SPECIFICATIONS**

Frequency	2400-2483.5MHz
Nominal Impedance	50 Ω
Return Loss	-4dB
Radiation Pattern	Omni
Gain	1.1dBi
Efficiency	66%
Polarization	linear
Power Withstanding	5W

MECHANICAL SPECIFICATIONS

Weight	0.03 g
Overall Length	3.2 [0.126] MM [INCHES]
Over all width	1.6 [0.063] MM [INCHES]
Over all thickness	1.1 [0.043] MM [INCHES]
MSL (Moisture Sensitivity Level)	1

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature	-40~+85° C
Storage Temperature	-40~+85° C
RoHS Compliant	Yes

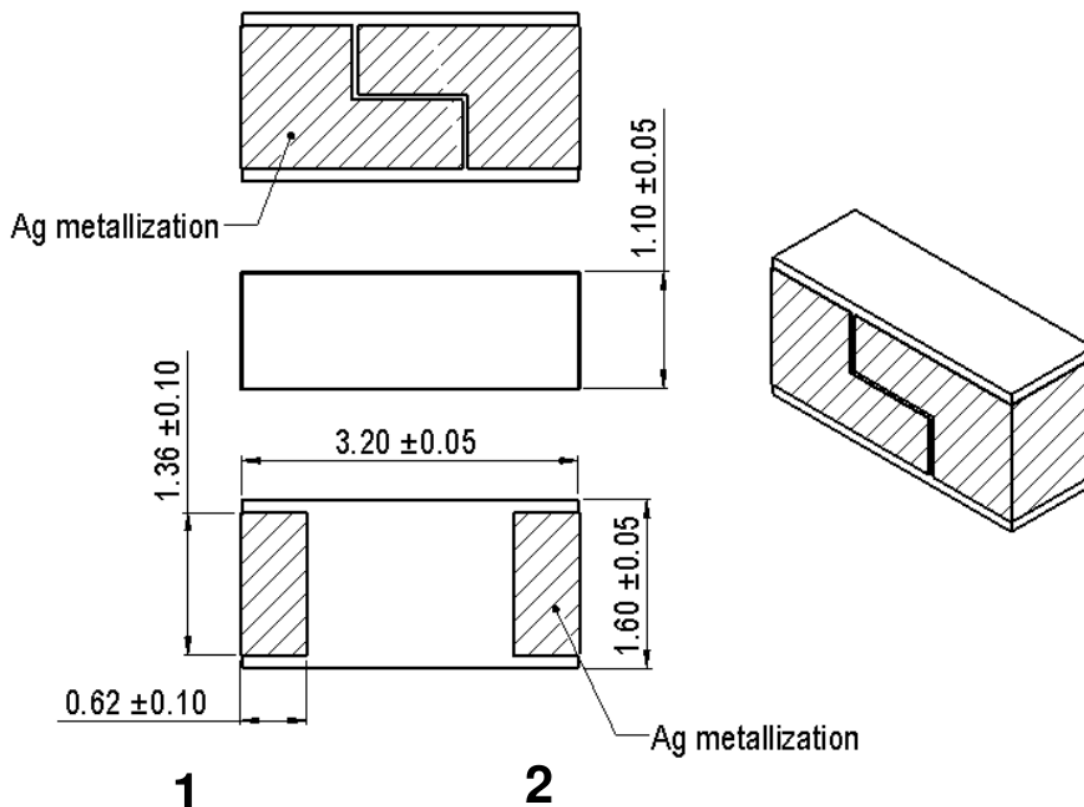
(*) All RF parameters measured on 80*37mm PCB with 4*4.25mm clearance in free space. No matching component used.

Series: Chip Antenna

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

PART NUMBER: W3008

MECHANICAL DRAWING AND TERMINAL CONFIGURATION



No.	Terminal Name	Terminal Dimensions
1	Feed /GND	0.62 x 1.36 mm
2	Feed /GND	0.62 x 1.36 mm
Antenna is symmetrical, either one of pads 1 or 2 can be used as feed terminal		

Note: This type of antenna is called loaded PIFA. One pad (on the bottom of the ceramic chip antenna) that feedline and GND are connected is a basic PIFA antenna structure. And, another pad on the other side that only GND is connected is for capacitive loading. Loaded capacitive value is optimized by the gap distance between two pads on the top surface. In PIFA, there is short mechanism usually in proximity to feed. This RF shorting affects impedance and current distribution mechanism of antenna. The actual antenna top face can seem to be mirrored, however it can be used same as the non-mirrored version. Please follow the design recommendation specified in this data sheet for either case.

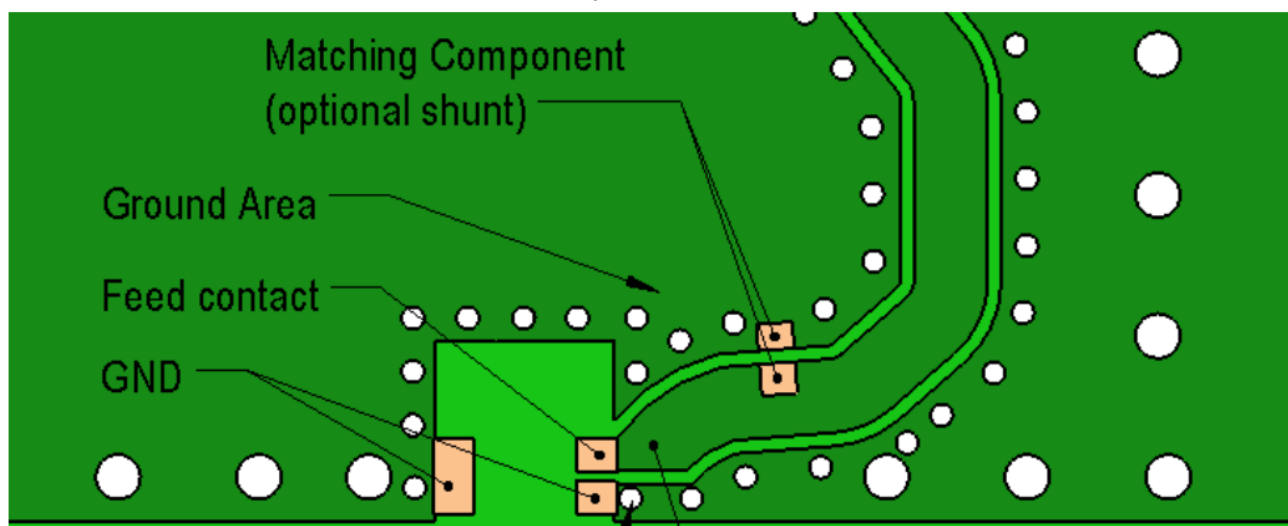
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

Series: Chip Antenna

PART NUMBER: W3008

MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Ground cleared under antenna, clearance area 4 mm x 4.25mm

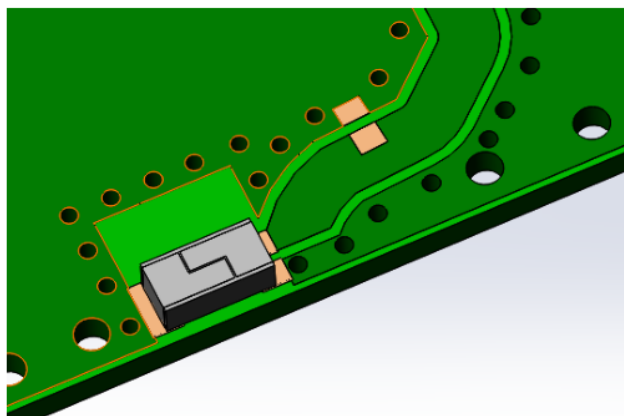


Ground Via Hole

Ground area should be surround with ground via holes

Feed line 50 Ohm

Any type of 50 Ohm feed line can be used. inner layers on feed line area need to designed to give 50 Ohm characteristics to feed line.



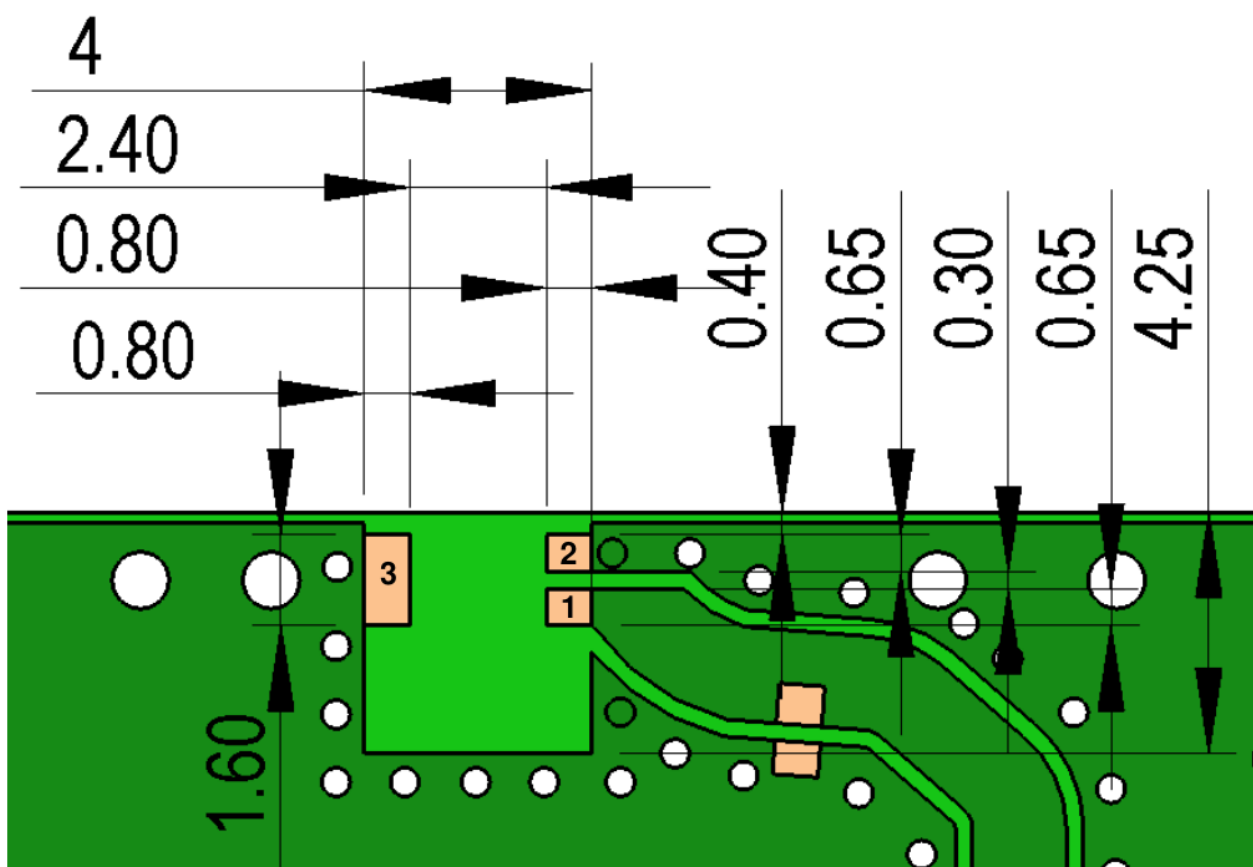
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

Series: Chip Antenna

PART NUMBER: W3008

MECHANICAL DRAWING AND TERMINAL CONFIGURATION

*Recommended Antenna Pad Dimensions on PCB Layout (top surface)
Ground cleared under antenna, clearance area 4 mm x 4.25 mm*



PCB contact pads

No.	Terminal Name	Terminal Dimensions
1	Feed	0,80 x 0,65 mm
2	GND	0,80 x 0,65 mm
3	GND	0,80 x 1,60 mm

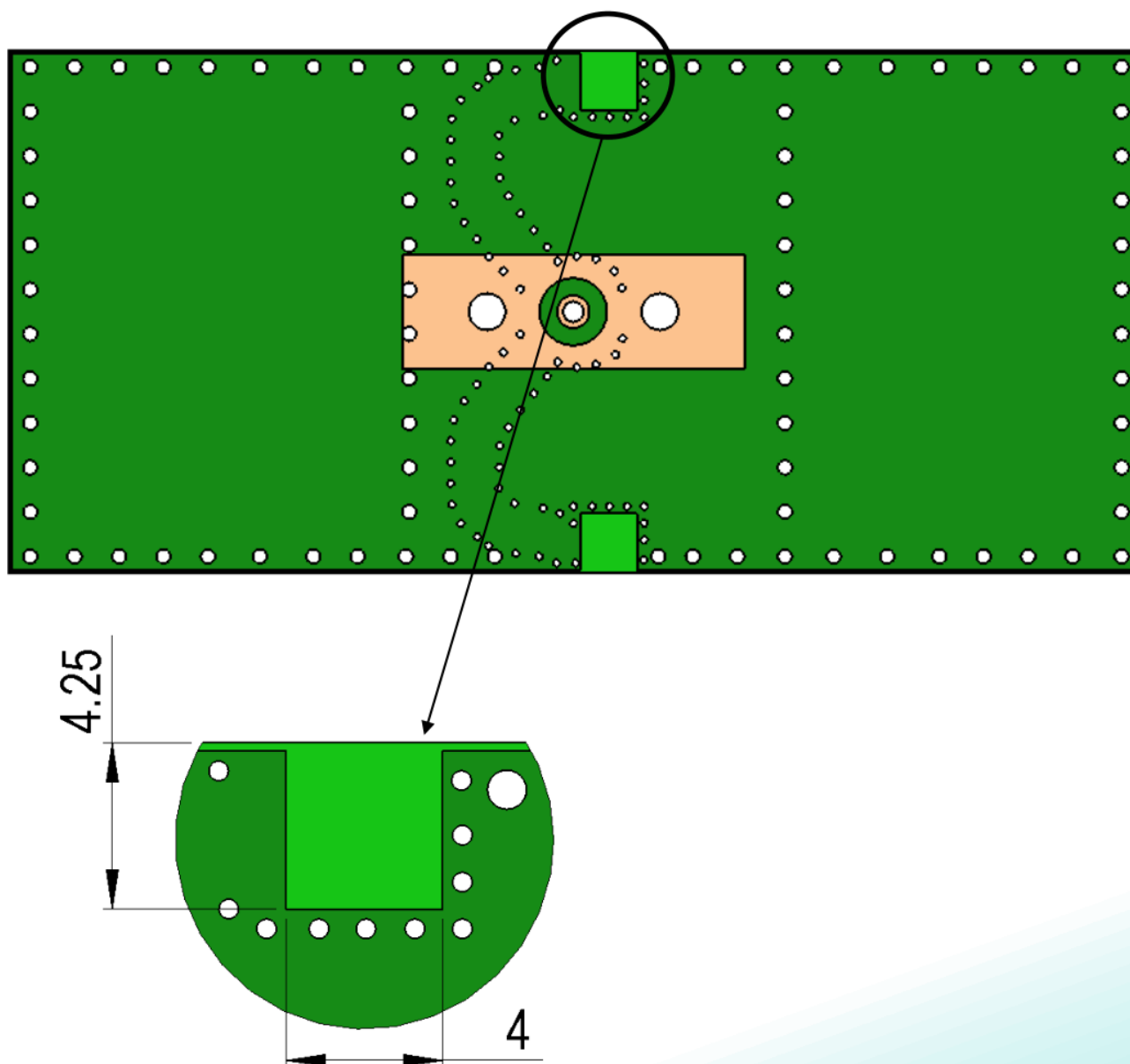
Series: Chip Antenna

Description: 2.4-2.4835GHz Ceramic SMT
antenna, 4x4.25mm keep out area

PART NUMBER: W3008

MECHANICAL DRAWING AND TERMINAL CONFIGURATION

*Recommended Antenna Pad Dimensions on PCB Layout (bottom surface)
Ground cleared under antenna, clearance area 4 mm x 4.25 mm*



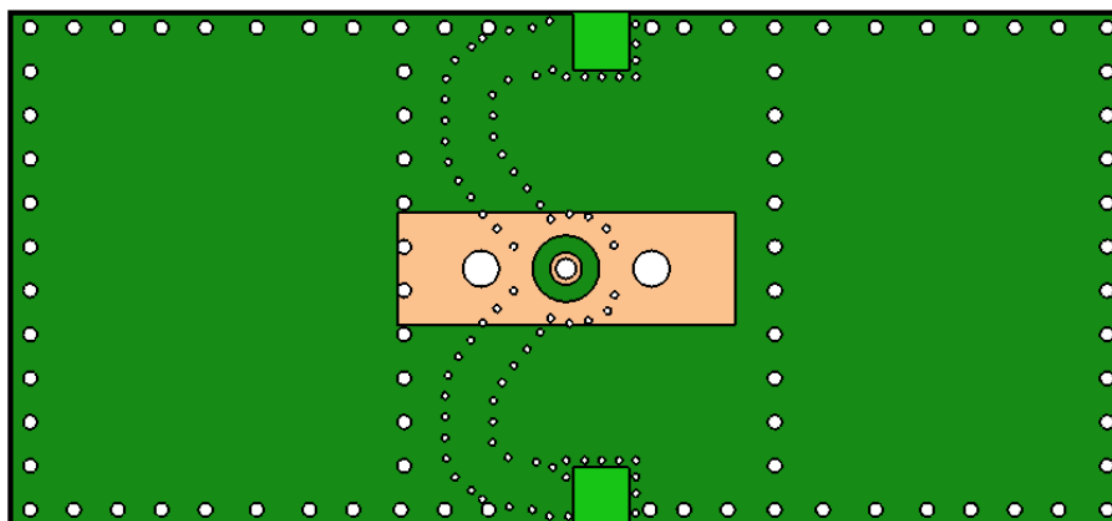
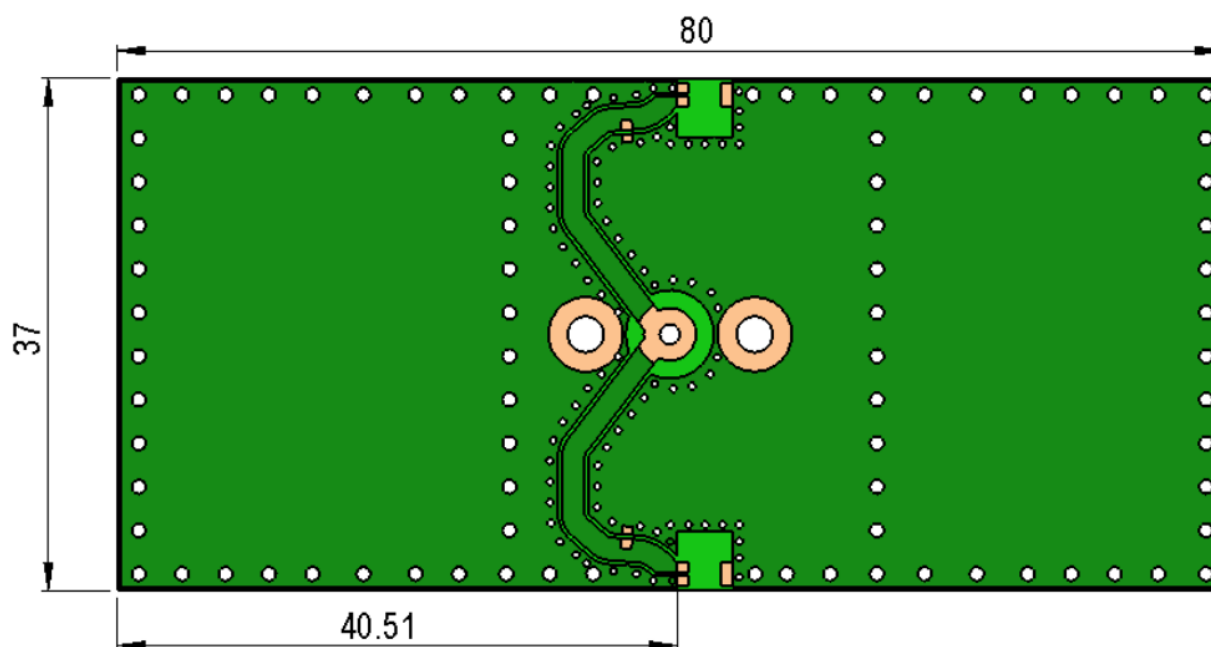
Description: 2.4-2.4835GHz Ceramic SMT
antenna, 4x4.25mm keep out area

Series: Chip Antenna

PART NUMBER: W3008

MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Recommended test board layout for electrical characteristic measurement, test board outline size 80 x 37mm



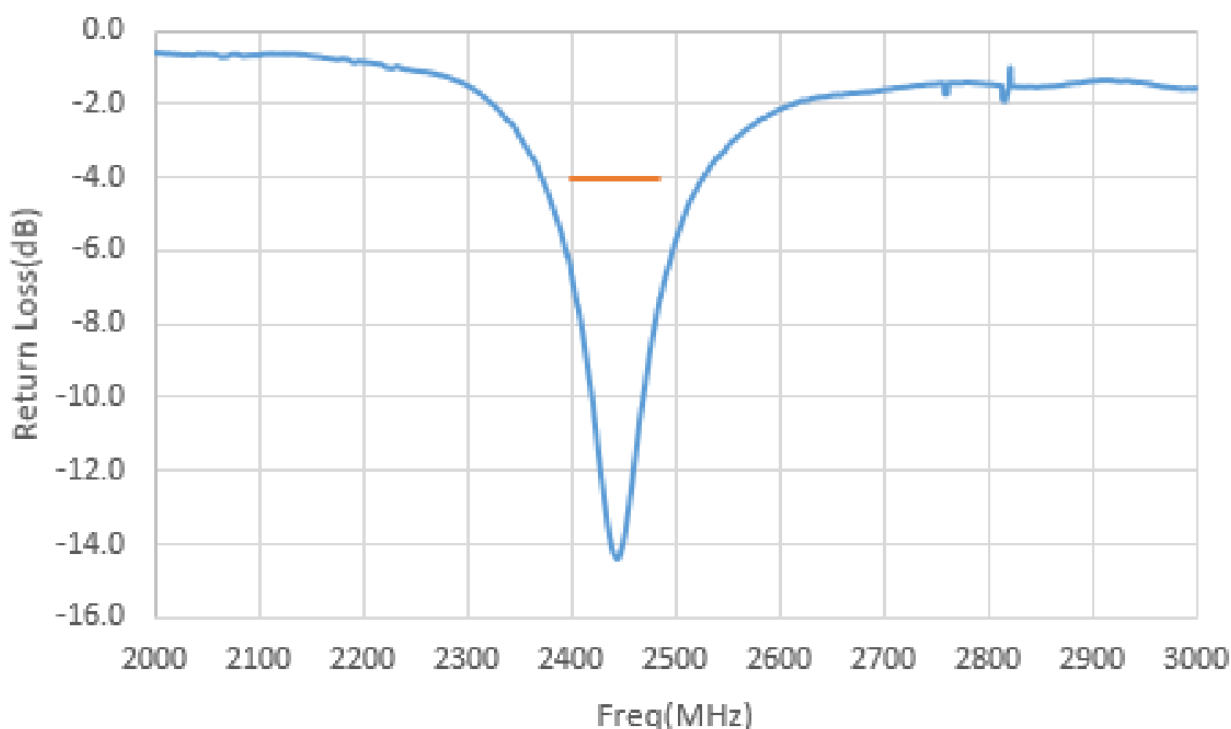
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

Series: Chip Antenna

PART NUMBER: W3008

CHARTS

Return loss



(*) All RF parameters measured on 80*37mm PCB with 4*4.25mm clearance in free space. No matching component used.

Issue: 1946

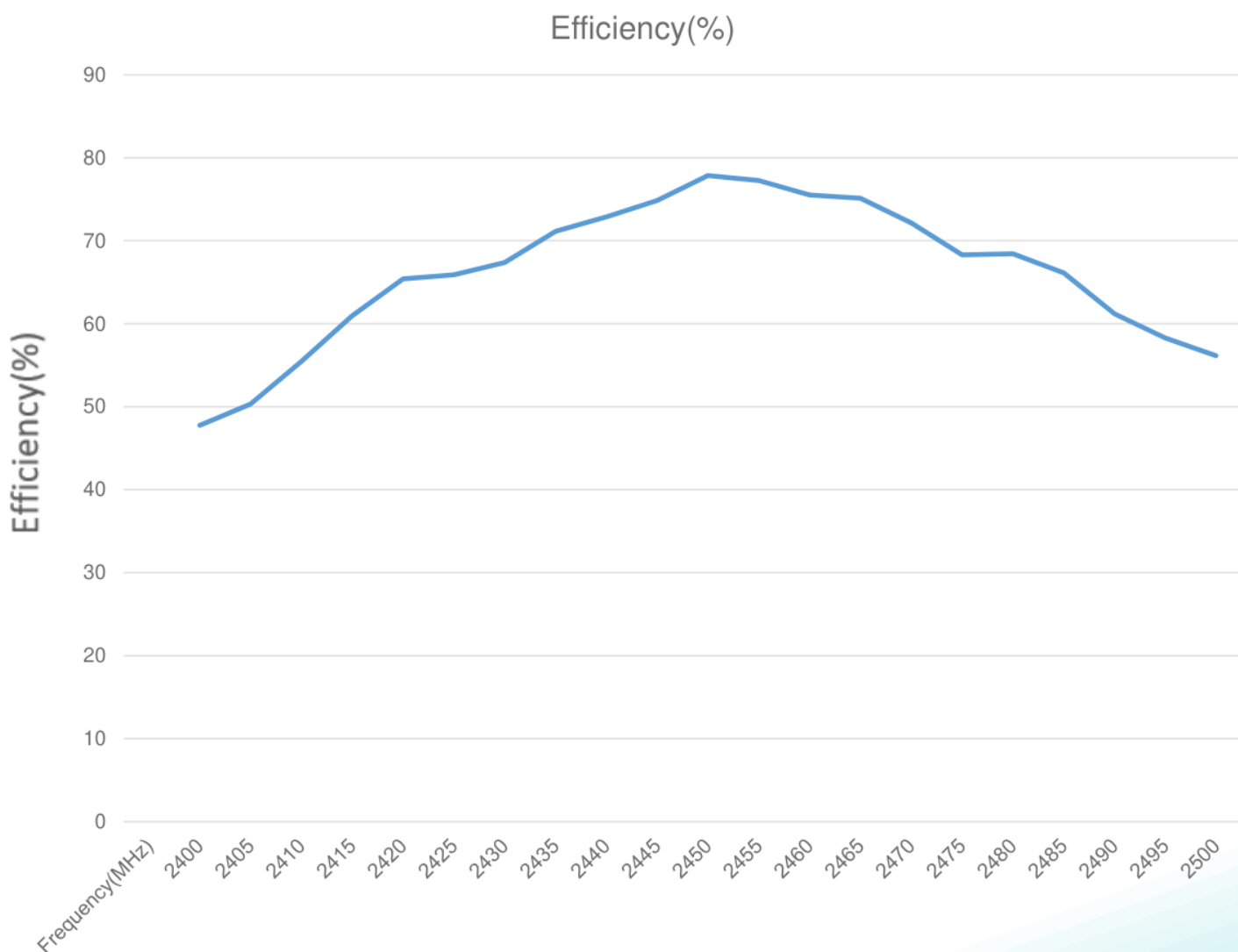
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CHARTS



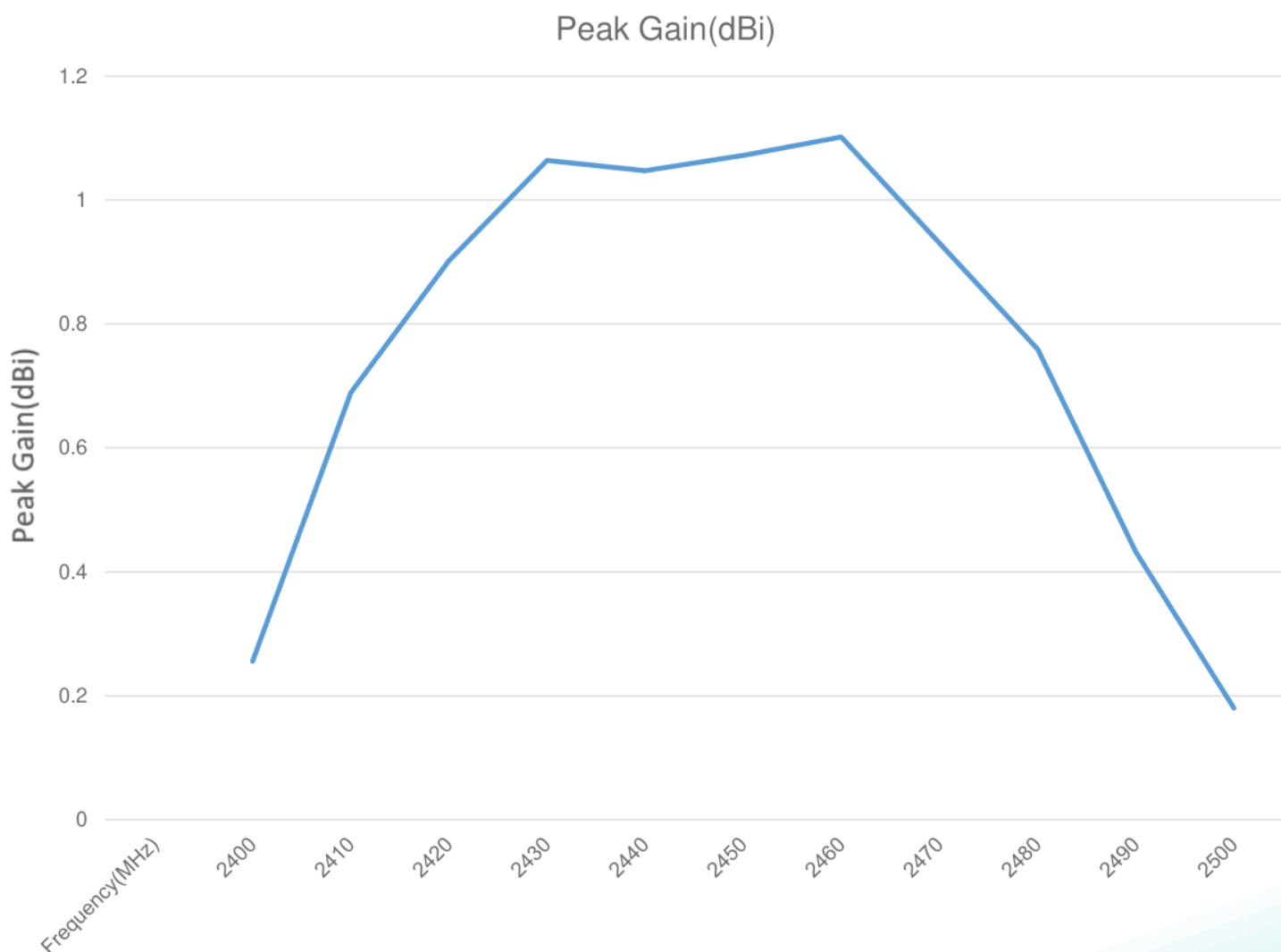
(*) All RF parameters measured on 80*37mm PCB with 4*4.25mm clearance in free space. No matching component used.

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

Series: Chip Antenna

PART NUMBER: W3008

CHARTS



(*) All RF parameters measured on 80*37mm PCB with 4*4.25mm clearance in free space. No matching component used.

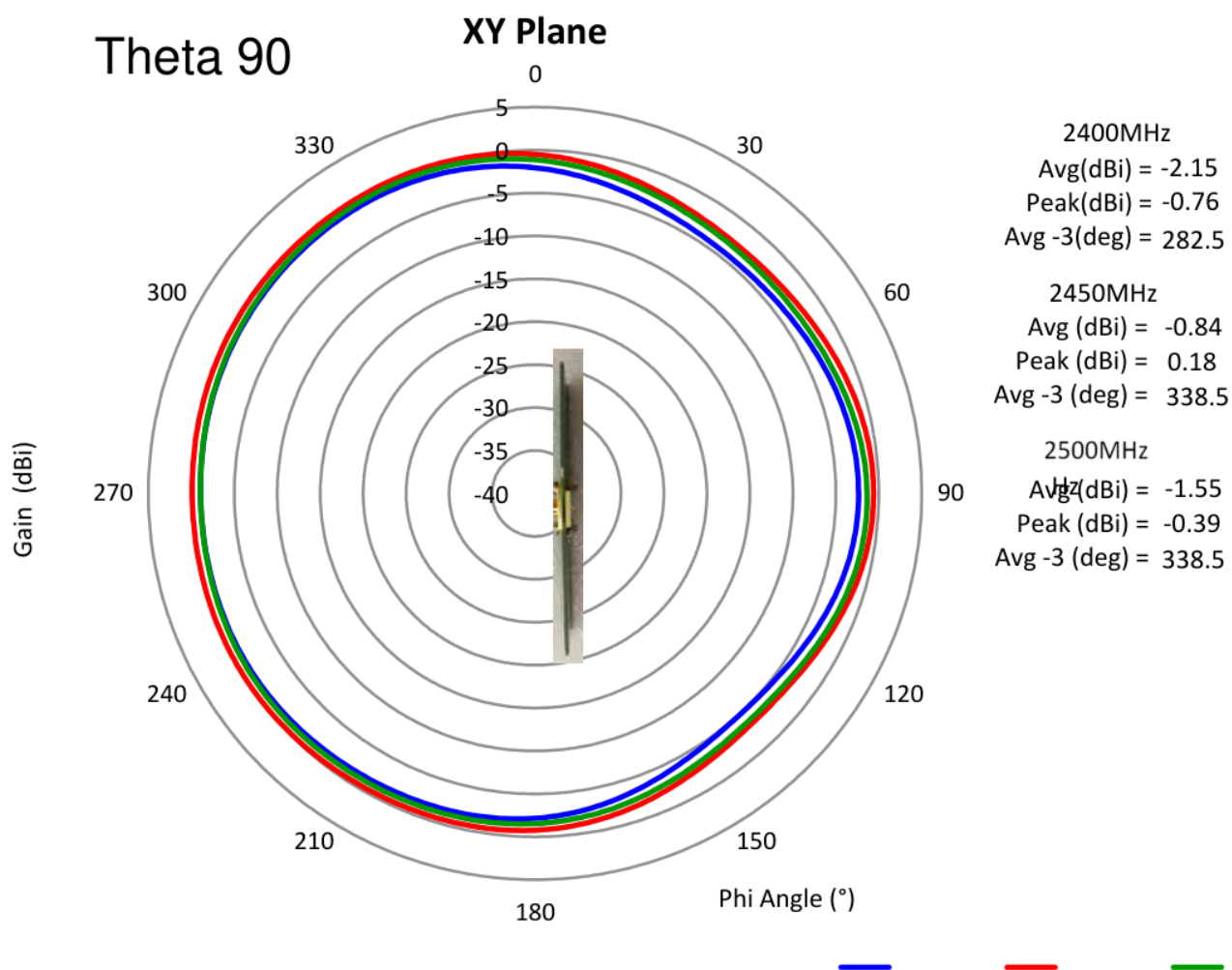
Series: Chip Antenna

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

PART NUMBER: W3008

CHARTS

Free Space Radiation Pattern



(*) All RF parameters measured on 80*37mm PCB with 4*4.25mm clearance in free space. No matching component used.

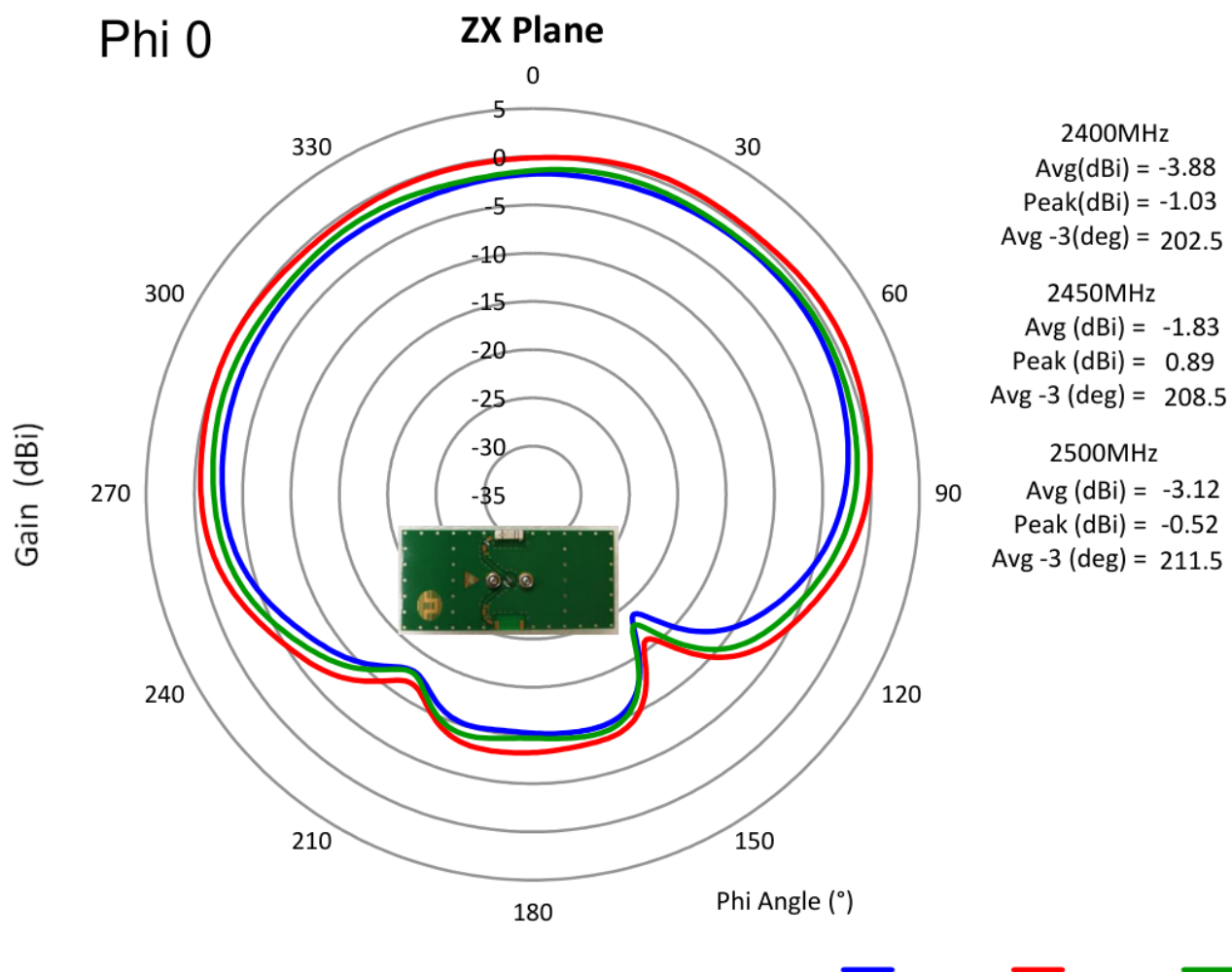
Series: Chip Antenna

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

PART NUMBER: W3008

CHARTS

Free Space Radiation Pattern



(*) All RF parameters measured on 80*37mm PCB with 4*4.25mm clearance in free space. No matching component used.

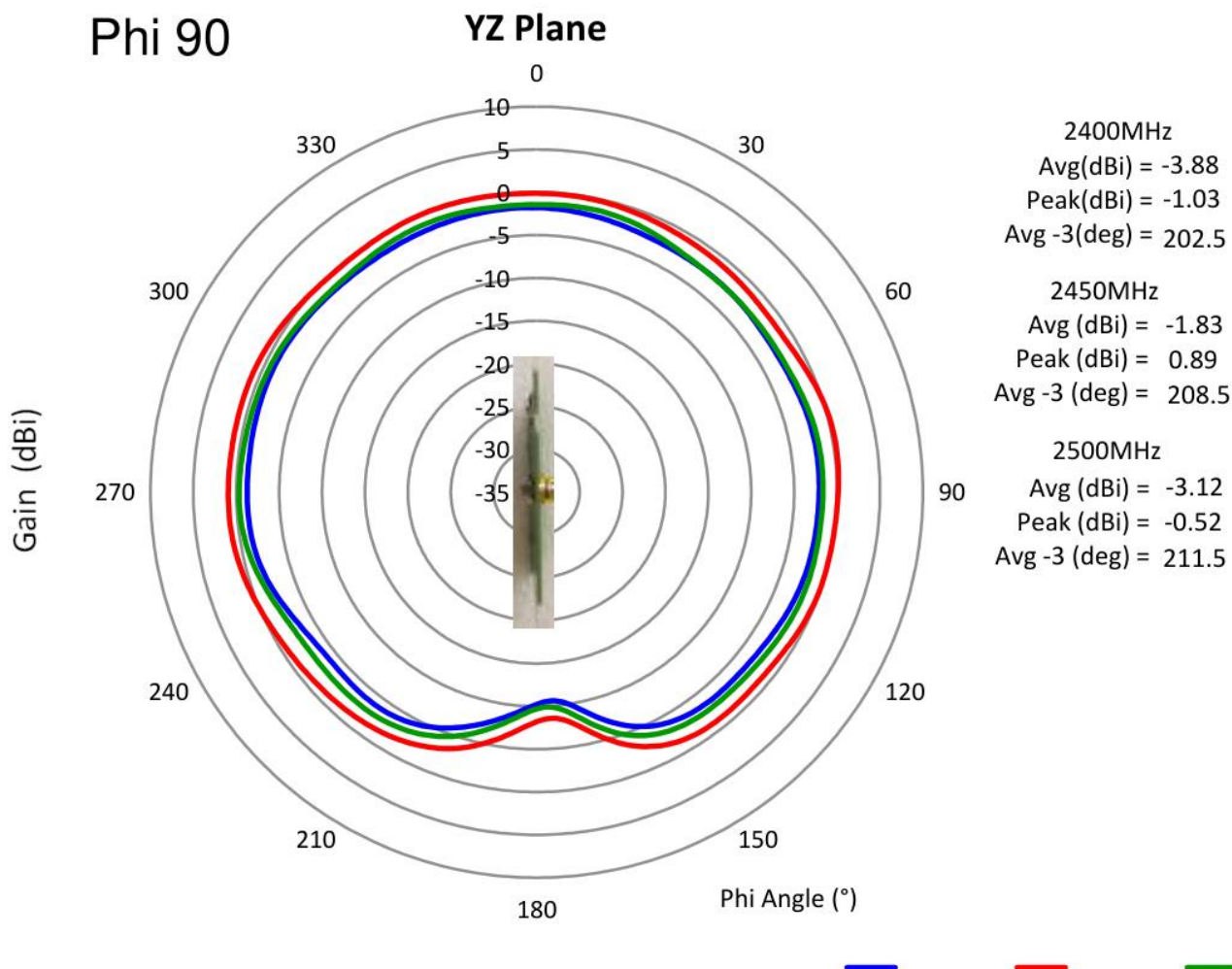
Series: Chip Antenna

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

PART NUMBER: W3008

CHARTS

Free Space Radiation Pattern



(*) All RF parameters measured on 80*37mm PCB with 4*4.25mm clearance in free space. No matching component used.

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

Series: Chip Antenna

PART NUMBER: W3008

Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile

presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s

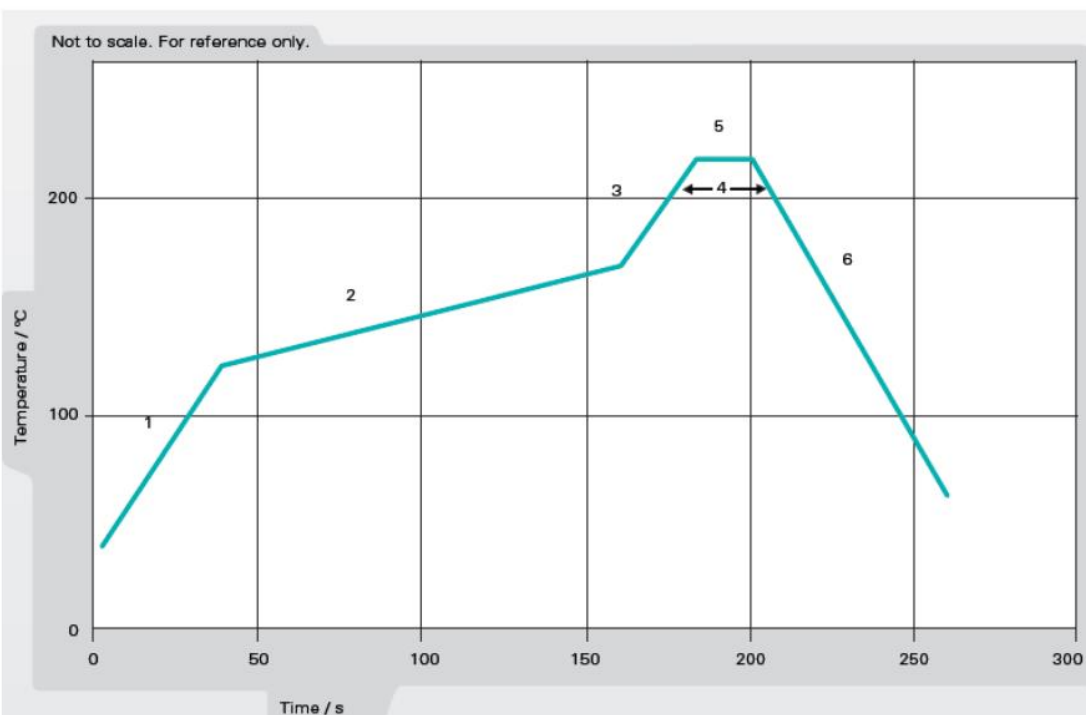


Figure 1. Minimum temperature profile recommendation for reflow soldering process

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

Series: Chip Antenna

PART NUMBER: W3008

Recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

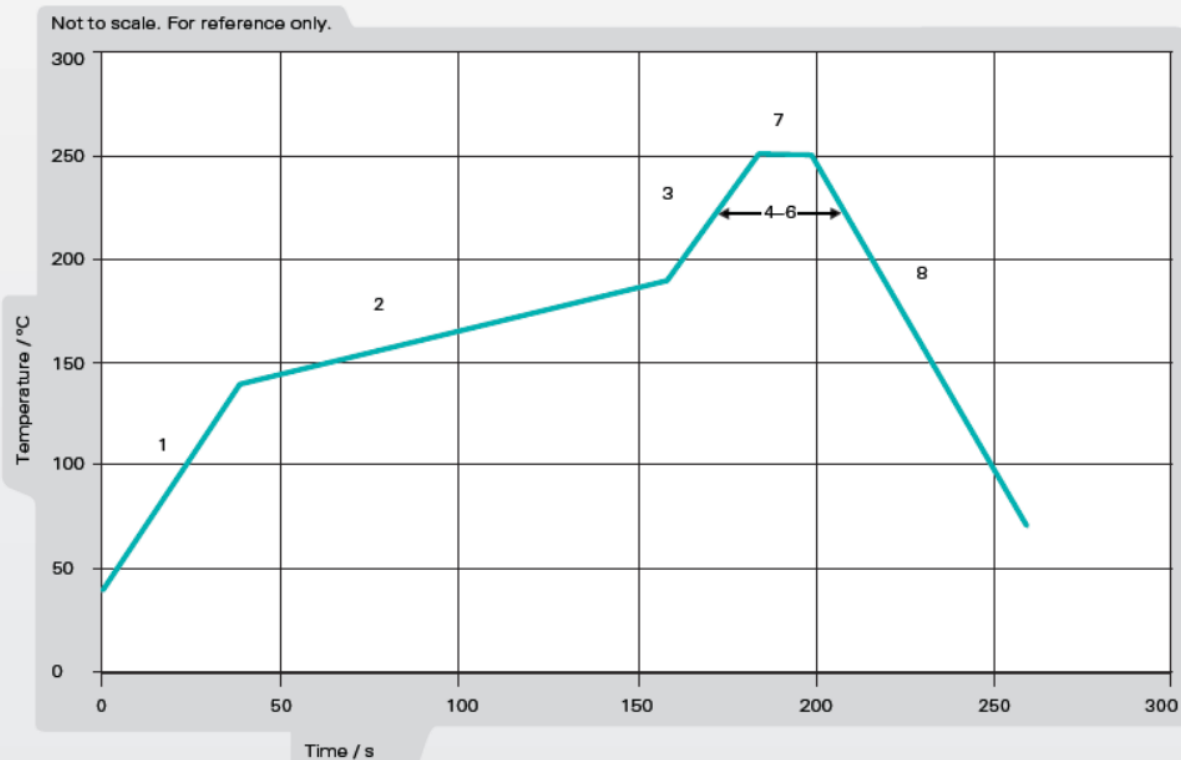


Figure 2. Maximum temperature profile recommendation for reflow soldering process

Series: Chip Antenna

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

PART NUMBER: W3008

PACKAGING-1

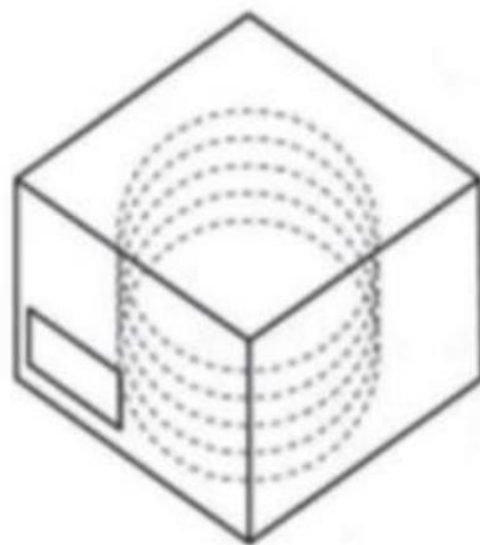
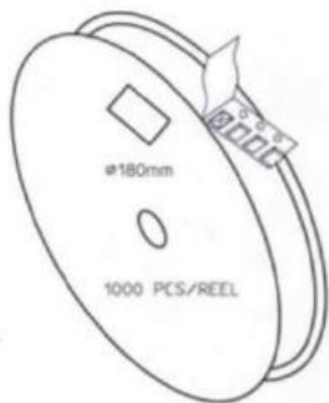
3000pcs antennas per 7" reel

5pcs 7" reel per inner package box

2pcs inner box per out box

Total 30000pcs antenna per out box

Out box size: 390mmx215mmx165mm



LEVEL

NOT MOISTURE SENSITIVE

1

These Devices do not require special storage conditions provided:

1. They are maintained at conditions equal to or less than 30°C and 85% RH.
2. They are solder reflowed at a peak body temperature which does not exceed 260°C.

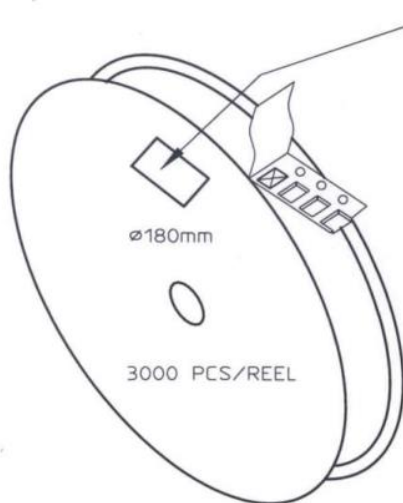
Note: Level 1 and body temperature defined by IPC/JEDEC J-STD-020

Series: Chip Antenna

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x4.25mm keep out area

PART NUMBER: W3008

PACKAGING-2



REEL LABEL INFORMATION:

- TRACEABILITY
- QUANTITY
- PRODUCT CODE

CARRIER TAPE H85-00125

width=8,00 depth=1,22

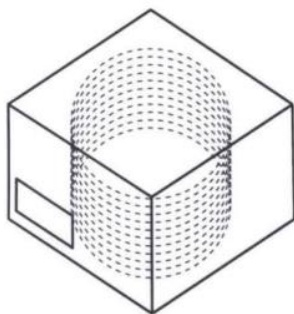
COVER TAPE H85-00126

width=5,60

LENGTH OF TAPE:

- Leader section: min 350 mm before component section
- Trailer section: min 40 mm after component section.

Empty part cavities at leader and trailer section of the tape must be sealed with top cover tape.



BOX H85-00128
(182x182x132)

1 pcs

- LABEL

1 pcs/BOX

REEL H85-00127
(D180, W12)

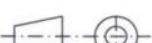
10 pcs

- REEL LABEL

1 pcs/REEL

MATERIAL

HANDLINGS

		RATIO	DRWN	090507 PeHa	H	
			DGNER		G	
			CHKD		F	
			APPRD		E	
			APPRD BY		D	
PRODUCT			H90-OY805			C
DENOMINATION						B
PACKING FORM					A	
			VERSION		MOD/DATE/NAME	